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No. 0429 P. 1

Atty. Docket No. CPAC 1017-5  
Appl. No. 10/632,552

OCT 04 2005

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Marcos KARNEZOS )

) Examiner: Chris C. CIU

Application No.: 10/632,552 )

) Group Art Unit: 2815

Filed: August 2, 2003 )

) Date: October 4, 2005

Title: Semiconductor multi-package module having )  
package stacked over die-up flip chip )  
ball grid array package and having wire )  
bond interconnect between stacked packages )

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being sent by facsimile to:  
Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, at the  
Central Fax No. 571 273-8300 on October 4, 2005.

Signed

  
Bill Keuncdy

MAIL STOP RCF  
COMMISSIONER FOR PATENTS  
P.O. Box 1450  
ALEXANDRIA, VA 22313-1450

**AMENDMENT**

Dear Sir:

In response to the Office action mailed April 4, 2005, kindly amend the application as follows.

Amendments to the Claims are reflected in the Listing of Claims which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.